IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	Material Compo © Copyright 2005. IF international and Pan	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.											
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Form Typ Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					rials and M	ials and Mfg Information					
Supplier Infor	mation																
Company name* Company unique				que ID [t			Unique ID Authority					Respons	Response Date*				
onsemi													2023-06-08				
Contact Name			Title - Conta	Title - Contact			Phone - Contact*					Email -	Email - Contact*				
Product-Env-Stev	wards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com						
				Title - Representative			Phone - Representative*					Email -	Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
Reques	ster Item Number	Mfr Item	Item Number Mfr Item Name				Effective Da	tive Date Version		Manufacturing Site			Weight*		UOM	Unit Type	
		74LCX16501M7		D 18-BIT BUS TRANSCEIVER 3V			2023-06-08	023-06-08 PH4			223.028		28	mg	Each		
Janufacturing	g Proccess Informat	ion															
Termina	inal Plating / Grid Array Material		Terminal Base Alloy J		J-STD-020 M	SL Rating	Peak Pr	Peak Process Body Temperature M		Max Time at Peak Tempera		nture Number of Reflow Cycles		eles			
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 2		2		260		C		30 seco		ds	3			
Comments																	
TTENTION: MS	SL 2 Rated item requires	Dry Pack (a	after electrical	l test)													
or more informa	tion regarding material o	composition	please refer to	page 3													

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.05	mg	Supplier	Silicon (Si)	7440-21-3		2.05	mg
Die Attach	0.255	mg	Supplier	Silver (Ag)	7440-22-4		0.1912	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.0637	mg
Lead Frame	85.28	mg	Supplier	Silver (Ag)	7440-22-4		0.938	mg
			Supplier	Magnesium (Mg)	7439-95-4		0.128	mg
			Supplier	Silicon (Si)	7440-21-3		0.554	mg
			В	Nickel (Ni)	7440-02-0		2.56	mg
			Supplier	Copper (Cu)	7440-50-8		81.1	mg
Mold Compound-Black	125.9	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		12.59	mg
			Supplier	Carbon Black (C)	1333-86-4		1.259	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		112.051	mg
Plating	8.153	mg	Supplier	Palladium (Pd)	7440-05-3		0.228	mg
			В	Nickel (Ni)	7440-02-0		7.77	mg
			Supplier	Gold (Au)	7440-57-5		0.155	mg
Wire Bond - Au	1.39	mg	Supplier	Gold (Au)	7440-57-5		1.39	mg